



## Challenges and Future Trends of Low-Dimensional Materials

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Deadline for manuscript submissions:

**closed (20 April 2024)**

### Message from the Guest Editors

Dear Colleagues,

Low-dimensional materials have attracted much attention in recent decades because of their extraordinary properties.

This Special Issue aims to collect recent advances in low-dimensional materials, including new low-dimensional structures predicted by new methods (e.g., machine learning), new low-dimensional materials synthesized by new experimental means, new properties of low-dimensional structures/materials (e.g., mechanical, optical, electronic properties) and their applications in engineering. Hybrid low-dimensional structures such as heterostructures and intercalated structures are also welcome. This Special Issue will also address what the current challenges of synthesis of low-dimensional materials are, what the development trends of the low-dimensional materials are in the coming years, and what new technologies and applications are on the horizon.





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## Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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